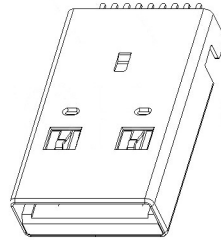
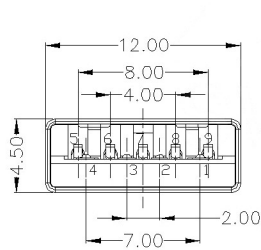


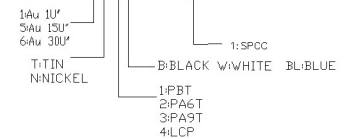
RECOMMENDED PCB LAYOUT

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	S_3A_SS Rx1	SUPER SPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	S_3A_SS Rx1		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	S_3A_SS Tx1	SUPER SPEED TRANSMITTER DIFFERENTIAL PAIR	
9	S_3A_SS Tx1		
Shell	Shell	CONNECTOR METAL SHELL	FIRST



Material
Housing Material: LCP, UL94V-0, blue
Contact Terminal: Copper Alloy
Metallic Shell: Spcc
Plating
Underplating: Nickel
Contact Plating: 1µ" Gold
Solder Tail: 100µ" Min. Tin
Metallic Shell: Nickel
Electrical
Voltage Rating: 100 V AC
Current Rating: 0.25A (Signal pins 2,3,5,6,7,8,9) 1.8A (Power Pins 1,4)
Contact Resistance: 30mΩ Max.
Insulation resistance: 1000MΩ Min.
Dielectric withstanding voltage: 100V AC/Minute
Mechanical
Mating Force: 35N (3.57kgf) Max
Unmating Force: 10N (1.02kgf) Min. initial, 8N min after test
Environmental and Processing
Operating Temperature: -40°C to +85°C

U237-09XN-4BLVS10-1



REVISIONS					UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE:		
Δ X					ANGLAR				USB 3.0		
Δ X					L ≤ 4	±5°		VIEW:	PART NO.:		
Δ X					4 < L ≤ 16	±0.2		UNIT: mm	DWG NO.:		
MARK	DESCRIPTION	DATE	REVISED	APPROVED	16 < L ≤ 63	±0.4		SIZE: A4	U237-09XN-4BLVS10-1		
					L > 63	±0.5			WEIGHT	SHEET	REVISION
	www.bodongkaiguan.net								1.0g	1/1	A0
	www.ksdkg.com								KOSOD TECHNOLOGY CO., LTD		